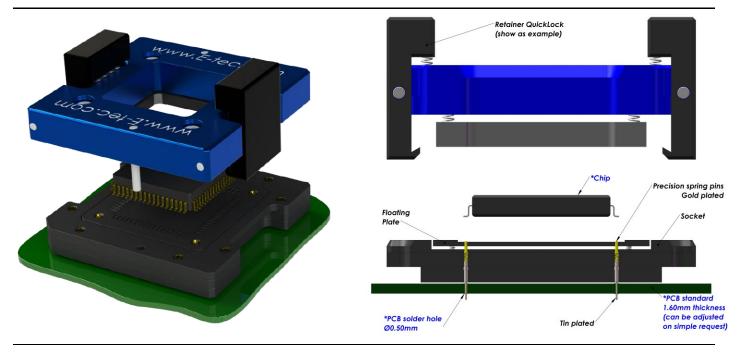
Through-hole (THT) soldering Test Socket

For SOP / DSO / SOIC / QFP / xQFP / Flatpack Package 1.27 mm pitch (from 1.27 mm upwards)





E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1270			
Application	Through-hole technology	Force	25 gr
Mounting	THT	Current rating	2.2 A
Bandwidth (GHz@-1dB)	3 GHz	Capacitance pF	< 1 pF
Contact resistance	<100mOhm	Inductance nH	< 2 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

How to order

Shape of tip Nbr of **Contact type Plating** Option code (see page 16-19) contacts D: Dead bug U: Concave 70 : Standard THT 95: Tin / Gold Depends on M: Multi frames Options: 72: Special THT to plug into MGS adapters 55: Gold / Gold ballcount of chip U: Multi packages P:Pointed Other on request S: Custom opening slot L: Locating pegs A: Alignment plate Retention frame type (Lid) (see page 12-15) Grid code / H: Heatsink Config. code S: ScrewLock Q: Open QuickLock (<200 contacts) F: Fan + Heatsink Will be given by the F:FastLock D: QuickLock (>200 contacts) P: Thermal drain pad factory after receipt B:SpringLock M: Injection Molded ClamShell of the chip datasheet W: Transparent lid I : Steel retention lid H: Open Clamshell Alu (<200 contacts) B: Aluminium retention lid J: Clamshell Alu (>200 contacts) T: Torque tool fixture L: Open Lever Clamshell Alu (>200 contacts) G: Handling button

